

## AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the above-referenced application.

### Listing of claims:

1. (Currently amended) A ~~The stencil of claim 11, for applying surface mount materials,~~  
comprising:  
  
    ~~at least two layers, said at least two layers comprising:~~  
  
        ~~at least one reservoir pocket; and~~  
  
        ~~at least one delivery aperture, wherein said at least one delivery aperture is~~  
~~adapted to deliver surface mount materials from said at least one reservoir pocket to a~~  
~~surface;~~  
  
    wherein said at least one reservoir pocket and said at least one delivery aperture  
include contiguous and impermeable sidewalls at an adjoining interface.
2. (Currently amended) The stencil of claim ~~[[1]]~~ 11, wherein said at least two layers further  
comprise:  
  
    at least one relief area, wherein said at least one relief area provides  
clearance for preexisting components on said surface so as to allow said at least one  
delivery aperture to contact said surface.
3. (Original) The stencil of claim 2 wherein said stencil comprises two layers,  
  
    an upper layer having at least one reservoir pocket; and  
  
    a lower layer having at least one delivery aperture and at least one relief area.

4. (Original) The stencil of claim 2 wherein said stencil comprises two layers:
- an upper layer having at least one reservoir pocket and at least one relief area; and
- a lower layer having at least one delivery aperture and at least one relief area,
- wherein the at least one relief area of the upper layer is connected to the at least one relief area of the lower layer.
5. (Original) The stencil of claim 2 wherein said stencil comprises three layers:
- an upper layer having at least one reservoir pocket;
- a middle layer having at least one relief area and at least one reservoir pocket; and
- a lower layer having at least one delivery aperture and at least one relief area,
- wherein the at least one reservoir pocket of the upper layer is connected to the at least one reservoir pocket of the middle layer, and the at least one relief area of the middle layer is connected to the at least one relief area of the lower layer.
6. (Cancelled)
7. (Currently amended) The stencil of claim ~~[[1]]~~ 11, wherein said at least two layers are manufactured out of metal.
8. (Cancelled)

9. (Currently amended) The stencil of claim 11, wherein said at least one delivery aperture is adapted to deliver surface mount materials selected from the group consisting of: adhesives, conducting adhesives, solder paste, and solder balls.
10. (Currently amended) The stencil of claim 11, wherein said at least two layers are attached to one another by means of a dry-mount aqueous solder mask laminate.
11. (Previously presented) A stencil for applying surface mount materials, comprising:  
at least two layers, said at least two layers comprising:  
at least one reservoir pocket; and  
at least one delivery aperture, wherein said at least one delivery aperture is adapted to deliver surface mount materials from said at least one reservoir pocket to a surface;  
wherein said at least two layers are aligned by means of at least one registration pin and at least one registration hole.
12. (Currently amended) The stencil of claim 11, wherein said stencil comprises two layers:  
an upper layer with at least one reservoir pocket; and  
a lower contacting layer with at least one delivery aperture, wherein said at least one delivery aperture delivers surface mount materials from said at least one reservoir pocket to said surface.

13. (Currently amended) The stencil of claim ~~[[1]]~~ 11, wherein said at least one reservoir pocket comprises:

a step-down pocket, wherein said step-down pocket is adapted to receive surface mount material applied directly into said step-down pocket and is further adapted to receive a device for forcing said surface mount material through said at least one delivery aperture.

14. (Currently amended) ~~A The stencil of claim 20, for applying surface mount materials,~~  
~~comprising:~~

~~an upper reservoir layer with at least one reservoir pocket;~~

~~a middle separation layer with at least one relief area, wherein said at least one relief area provides clearance for preexisting components mounted on a surface, and wherein said middle separation layer further comprises at least one reservoir through pocket connected to said at least one reservoir pocket in said upper layer; and~~

~~a lower contacting layer with at least one delivery aperture, wherein said at least one delivery aperture is adapted to deliver measured surface mount materials from said at least one reservoir pocket by means of said at least one reservoir through pocket to said surface, and wherein said lower contacting layer further comprises at least one relief opening which is connected to said at least one relief area in said middle separation layer;~~

~~wherein said at least one reservoir pocket and said at least one delivery aperture include contiguous and impermeable sidewalls at an adjoining interface.~~

15. (Cancelled)

16. (Currently amended) The stencil of claim [[14]] 20, wherein said upper layer, middle layer and lower layer are manufactured out of metal.

17. (Cancelled)

18. (Currently amended) The stencil of claim [[14]] 20, wherein said at least one delivery aperture is adapted to deliver surface mount materials selected from the group consisting of: adhesives, conducting adhesives, solder paste, and solder balls.

19. (Currently amended) The stencil of claim [[14]] 20, wherein said upper layer, middle layer, and lower layer are attached to one another by means of a dry-mount aqueous solder mask laminate.

20. (Previously presented) A stencil for applying surface mount materials, comprising:

an upper reservoir layer with at least one reservoir pocket;

a middle separation layer with at least one relief area, wherein said at least one relief area provides clearance for preexisting components mounted on a surface, and wherein said middle separation layer further comprises at least one reservoir through pocket connected to said at least one reservoir pocket in said upper layer; and

a lower contacting layer with at least one delivery aperture, wherein said at least one delivery aperture is adapted to deliver measured surface mount materials from said at least one reservoir pocket by means of said at least one reservoir through pocket to said surface, and wherein said lower contacting layer further comprises at least one relief opening which is connected to said at least one relief area in said middle separation layer;

wherein said upper layer, middle layer, and lower layer are aligned by means of at least one registration pin and at least one registration hole.

21. (Currently amended) A ~~The stencil of claim 25, for applying solder balls in a desired pattern onto a substrate, comprising:~~

~~an upper layer with at least one ball drop reservoir aperture; and~~

~~a lower contacting layer with at least one relief delivery aperture, wherein said relief delivery aperture is adapted to draw solder material from said at least one ball drop reservoir aperture and provides clearance for flux on pad sites on said substrate;~~

~~wherein said at least one ball drop reservoir aperture and said at least one relief delivery aperture include contiguous and impermeable sidewalls at an adjoining interface.~~

22. (Currently amended) The stencil of claim ~~[[21]]~~ 25, wherein said upper layer and lower layer are manufactured out of metal.
23. (Cancelled)
24. (Currently amended) The stencil of claim ~~[[21]]~~ 25, wherein said upper layer and lower layer are attached to one another by means of a dry-mount aqueous solder mask laminate.
25. (Previously presented) A stencil for applying solder balls in a desired pattern on a substrate, comprising:
- an upper layer with at least one ball drop reservoir aperture; and
  - a lower contacting layer with at least one relief delivery aperture, wherein said relief delivery aperture is adapted to draw solder material from said at least one ball drop reservoir aperture and provides clearance for flux on pad sites on said substrate;
- wherein said upper layer and lower layer are aligned by means of at least one registration pin and at least one registration hole.

26. (Currently amended) A The method of claim 29, for depositing surface mount materials  
onto a surface, comprising the steps of:

~~matching relief areas in a stencil with preexisting surface mount components on a  
surface;~~

~~affixing the stencil to the surface;~~

~~applying surface mount materials to said stencil such that said surface mount  
materials fill reservoir pockets in said stencil; and~~

~~depositing surface mount materials onto said surface through delivery apertures  
on said stencil, said delivery apertures drawing said surface mount material from said  
reservoir pockets.~~

wherein said reservoir pockets and said delivery apertures include contiguous and  
impermeable sidewalls at adjoining interfaces.

27. (Currently amended) The method of claim [[26]] 29, wherein said surface mount materials  
are selected from the group consisting of: adhesives, conducting adhesives, solder paste,  
and solder balls.

28. (Currently amended) The method of claim [[26]] 29, wherein said surface is selected from  
the group consisting of: a printed circuit board, a flexible circuit, and a wafer.



29. (Previously presented) A method for depositing surface mount materials onto a surface, comprising:
- matching relief areas in a stencil with preexisting surface mount components on a surface;
  - affixing the stencil to the surface;
  - applying surface mount materials to said stencil such that said surface mount materials fill reservoir pockets in said stencil;
  - depositing surface mount materials onto said surface through delivery apertures on said stencil, said delivery apertures drawing said surface mount material from said reservoir pockets; and
  - aligning at least an upper layer and a lower layer of said stencil using at least one registration pin and at least one registration hole.
30. (Previously presented) The stencil of claim 1, wherein said contiguous and impermeable sidewalls include a solvent-resistant resin.
31. (Previously presented) The stencil of claim 14, wherein said contiguous and impermeable sidewalls include a solvent-resistant resin.
32. (Previously presented) The stencil of claim 21, wherein said contiguous and impermeable sidewalls include a solvent-resistant resin.
33. (Previously presented) The method of claim 26, wherein said contiguous and impermeable sidewalls include a solvent-resistant resin.